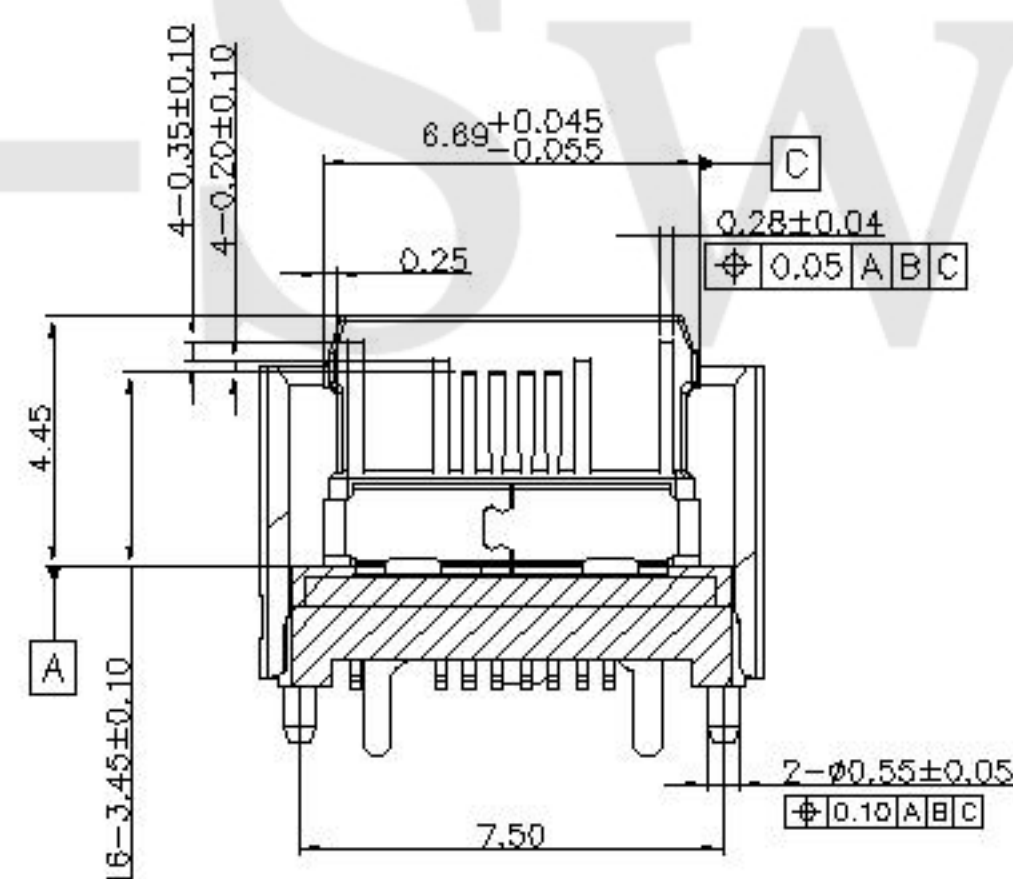
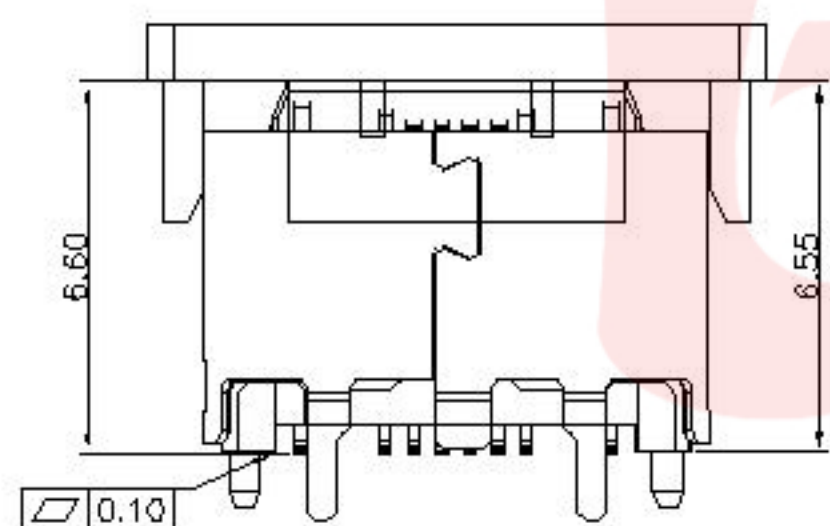
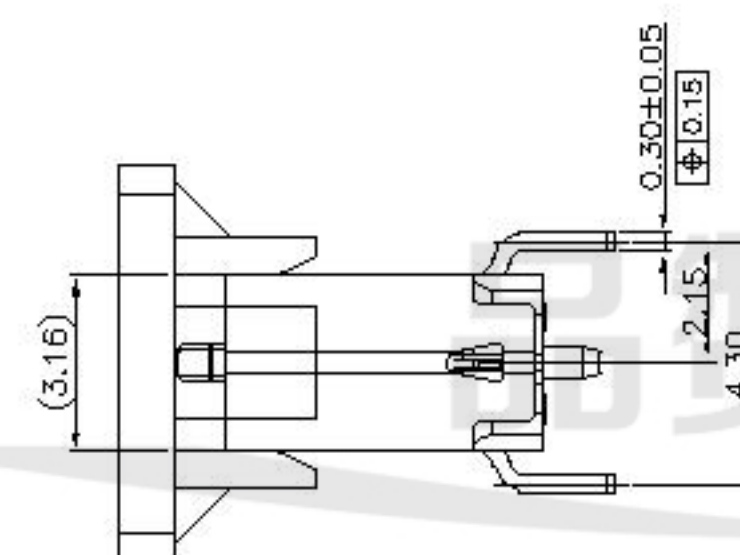
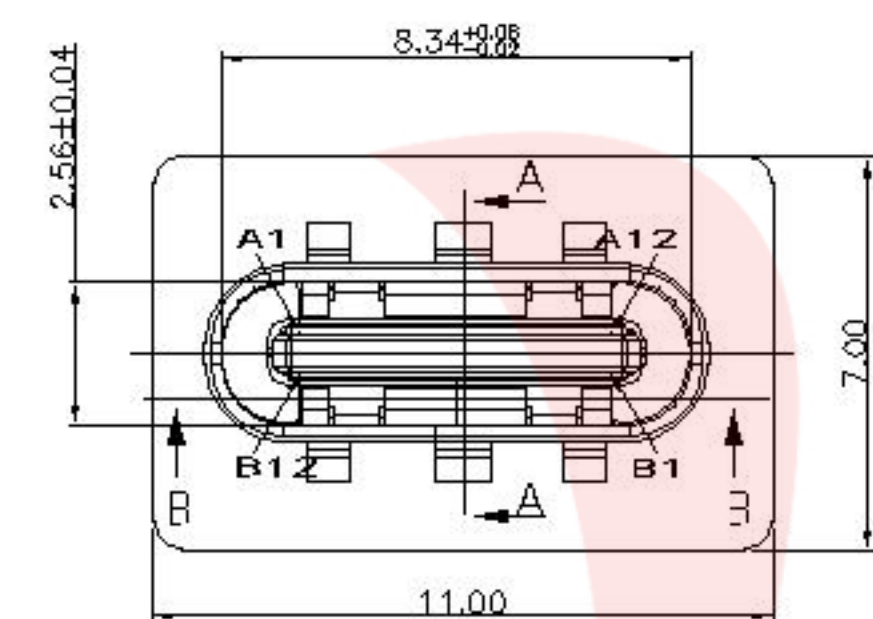
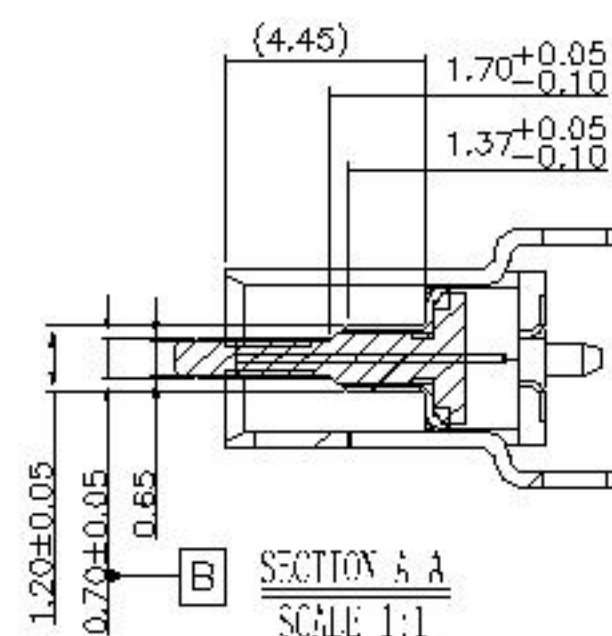
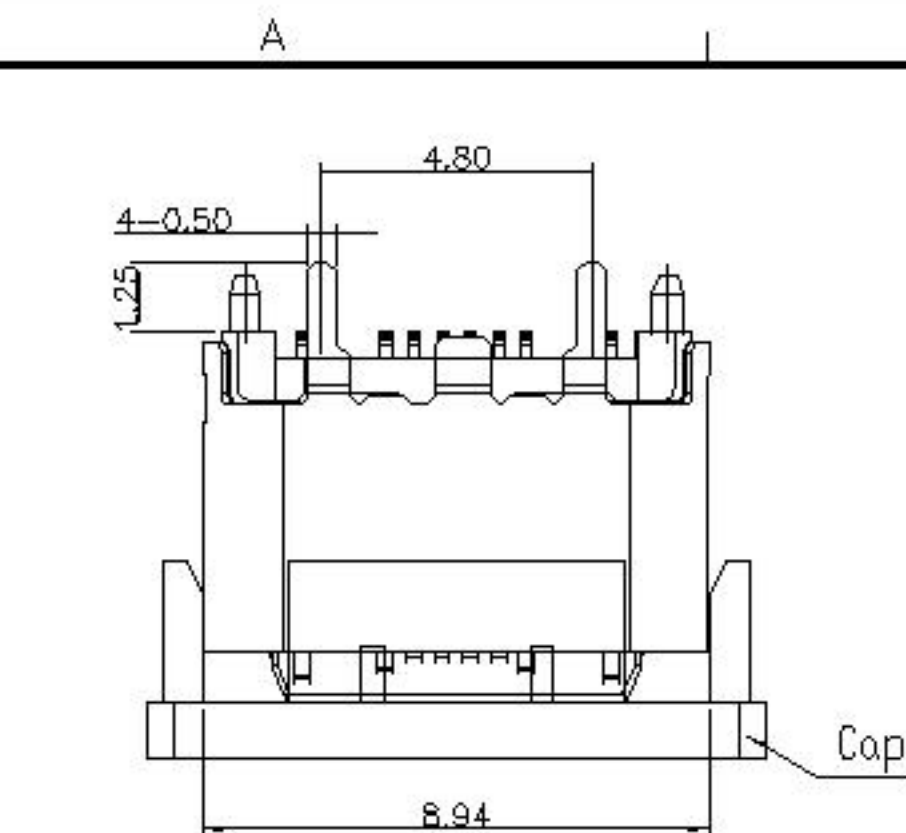
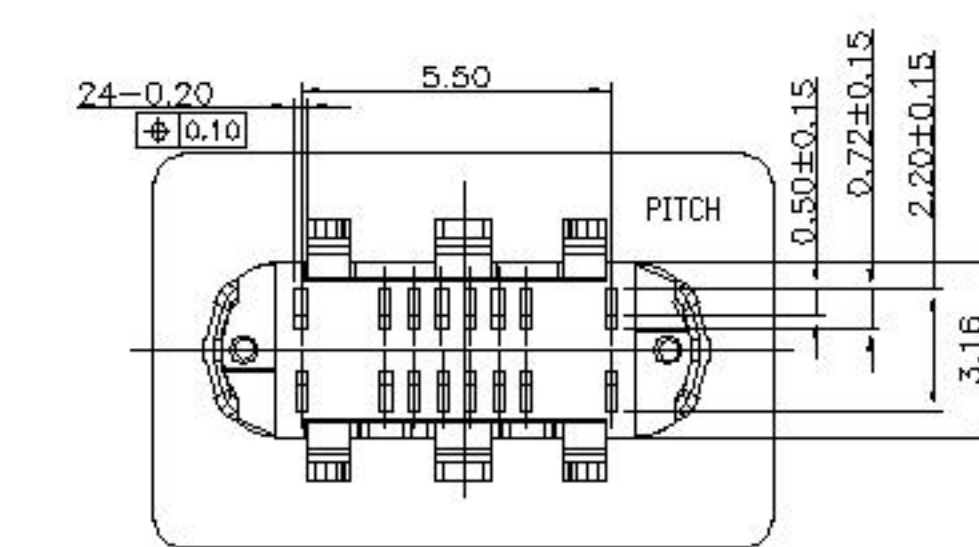


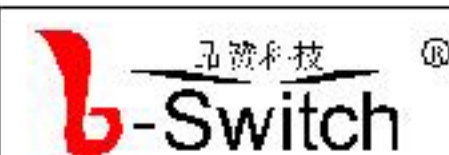
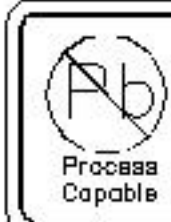


SECTION B-B
SCALE 1:1



NOTES:

1. MATERIAL:
MOLDING: LCP UL94 V-0
CONTACT: COPPER ALLOY.
GOLD PLATING ALL OVER 50u" Min NICKEL
AND 100u" Min Tin ALL OVER 50u" Min NICKEL
ON SOLDER AREA
SHELL: SUS304-H, T=0.30±0.03mm
50u" NICKEL PLATING OVER ALL.
SHIELD: SUS304-H, T=0.12±0.03mm
2. MECHANICAL:
INSERTION: 5~20N.
EXTRACTION: 8~20N AFTER TEST.
DURABILITY: 10000 CYCLES
3. ELECTRICAL:
CURRENT: 5A FOR VBUS;
1.25A FOR GND PIN.
0.25A FOR OTHER.
VOLTAGE: 20 V MAX
WITHSTANDING VOLTAGE: 100V AC R. M. S
CONTACT RESISTANCE: 40mΩ MAX.
INSULATION RESISTANCE: 100MΩ MIN.
4. ENVIRONMENTAL
TEMPERATURE RANGE -55° C ~ +85° C



G-Switch Electronic (HongKong) CO., Ltd.

Unless otherwise specified, Tolerance:
X. ±0.30
X.x ±0.20
X.xx ±0.15
X.xxx ±0.10
Angles ±3°

DESIGN: FengFengChen	DATE: 2020.05.09	Molde code:	
CHECKED	DATE	GT-USB-7055A	
APPROVED	DATE		
http://www.dg-switch.com		REV.: X1	SCALE: 4:1
TEL: 0769-82388879		SIZE: A4	SHEET: 1/1

